

Application No.: 10/737,412

Docket No.: JCLA10726

**AMENDMENT****In the Claims:**

Please amend the claims as follows:

**Claims 1-16 (cancelled)**

Claim 17. (Currently amended) A multi-layered substrate, at least comprising:

a lamination structure having at least a through-hole, wherein the through-hole passes through and links up with the surfaces of the lamination structure;

a first mask layer formed on one surface of the lamination structure, wherein the first mask layer has at least a first opening;

a second mask layer formed on another surface of the lamination structure, wherein the second mask layer has at least a second opening; and

a vertical routing structure comprising a conductive rod and a conductive layer, wherein the conductive rod occupies the interior of the through-hole and the ends of the conductive rod completely fill the first opening and the second opening respectively, and the conductive layer occupies the space between the interior surface of the through-hole and the conductive rod, wherein the conductive layer extends to cover a peripheral surface of the second opening and a portion of the second mask layer around the second opening.

Claim 18. (original) The multi-layered substrate of claim 17, wherein the second opening has a diameter greater than the through-hole.

**Claim 19. (Cancelled)**

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Claim 20. (original) The multi-layered substrate of claim 17, wherein one end of the conductive rod serves as a bump, a pre-solder block or a contact.

Claim 21. (original) The multi-layered substrate of claim 17, wherein the substrate furthermore comprises a bump attached to one end of the conductive rod.

Claim 22. (original) The multi-layered substrate of claim 17, wherein the substrate furthermore comprises a pre-solder block attached to one end of the conductive rod.

Claim 23. (original) The multi-layered substrate of claim 17, wherein the substrate furthermore comprises a solder ball attached to one end of the conductive rod.

Claim 24. (original) The multi-layered substrate of claim 17, wherein the lamination structure furthermore comprises at least a buried circuit layer that connects electrically with the conductive layer.